RELIABILITY REPORT

FOR

MAX4257ESA+
(MAX4249-MAX4257)

PLASTIC ENCAPSULATED DEVICES

January 23, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX4257ESA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4249-MAX4257 low-noise, low-distortion operational amplifiers offer rail-to-rail outputs and single-supply operation down to 2.4V. They draw 400µA of quiescent supply current per amplifier while featuring ultra-low distortion (0.0002% THD), as well as low input voltage-noise density (7.9nV per root-Hz) and low input current-noise density (0.5fA per root-Hz). These features make the devices an ideal choice for portable/battery-powered applications that require low distortion and/or low noise. For additional power conservation, the MAX4249/MAX4251/MAX4253/MAX4256 offer a low-power shutdown mode that reduces supply current to 0.5µA and puts the amplifiers' outputs into a high-impedance state.

The MAX4249-MAX4257's outputs swing rail-to-rail and their input common-mode voltage range includes ground. The MAX4250-MAX4254 are unity-gain stable with a gain-bandwidth product of 3MHz. The MAX4249/MAX4255/MAX4256/MAX4257 are internally compensated for gains of 10V/V or greater with a gain-bandwidth product of 22MHz. The single MAX4250/MAX4255 are available in space-saving 5-pin SOT23 packages. The MAX4252 is available in an 8-bump chip-scale package (UCSP(tm)) and the MAX4253 is available in a 10-bump UCSP. The MAX4250AAUK comes in a 5-pin SOT23 package and is specified for operation over the automotive (-40°C to +125°C) temperature range.

II. Manufacturing Information

A. Description/Function:	UCSP, Single-Supply, Low-Noise, Low-Distortion, Rail-to-Rail Op Amps
B. Process:	B12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Carsem Malaysia, UTL Thailand, ATP Philippines, Unisem Malaysia
F. Date of Initial Production:	January 23, 1998

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-3001-0078
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	132°C/W
M. Multi Layer Theta Jc:	38°C/W

IV. Die Information

A. Dimensions:	58 X 75 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 125 \times 2} \quad \text{(Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 8.6 \times 10^{-9}$

λ = 8.6 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the B12 Process results in a FIT Rate of 3.13 @ 25C and 54.16 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The OP67-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1

Reliability Evaluation Test Results

MAX4257ESA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	125	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data